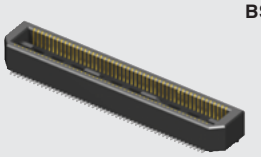
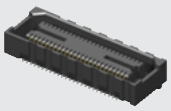
samtec

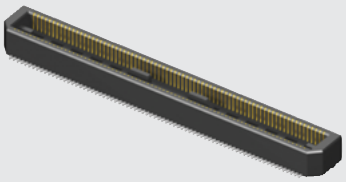
E.L.P.™
EXTENDED LIFE PRODUCT
10 year Mixed Flowing Gas with 50µ" Gold
Call Samtec for maximum mated cycles



BTS–050–01–F–D–A



BSS–025–01–L–D–A



BTS–075–01–L–D–A

(0,635 mm) .025"

BTS, BSS SERIES

BASIC BLADE & BEAM HEADER & SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?BTS or www.samtec.com?BSS

Insulator Material: Liquid Crystal Polymer
Terminal Material (BTS): Phosphor Bronze
Contact Material (BSS): Phosphor Bronze
Plating: Au or Sn over 50µ" (1,27 µm) Ni
Current Rating: 1.8 A per pin (1 pin powered per row)
Operating Temp Range: -55°C to +125°C
RoHS Compliant: Yes

Processing:

Lead-Free Solderable: Yes
SMT Lead Coplanarity: (0,10 mm) .004" max
Board Stacking: For applications requiring more than two connectors per board or 100 positions or higher, contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

FILE NO. E111594

MATED HEIGHT

LEAD STYLE	MATED HEIGHT*
–01	(5,00) .197

*Processing conditions will affect mated height.

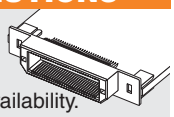
ALSO AVAILABLE (MOQ Required)

- 30µ" (0,76 µm) Gold
- Other platings
- Other positions

Contact Samtec.

OTHER SOLUTIONS

Edge Mount capability. Call for availability.



Note: Some lengths, styles and options are non-standard, non-returnable.

BTS – NO. OF POSITIONS PER ROW – 01 – PLATING OPTION – D – A – OTHER OPTION

Mates with: BSS

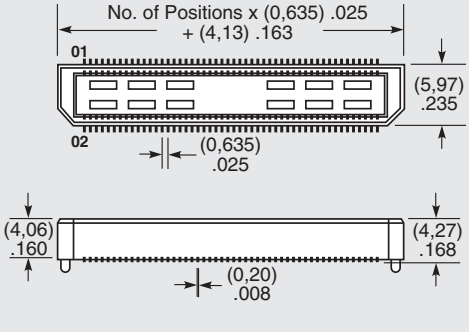
–025, –050, –075, –100

–F = Gold Flash on contact, Matte Tin on tail

–L = 10µ" (0,25 µm) Gold on contact, Matte Tin on tail

–K = (7,00 mm) .275" DIA Polyimide Film Pick & Place Pad

–TR = Tape & Reel (–100 positions maximum)



RUGGEDIZED by SAMTEC
• Passes 10 year MFG

BSS – NO. OF POSITIONS PER ROW – 01 – PLATING OPTION – D – A – OTHER OPTION

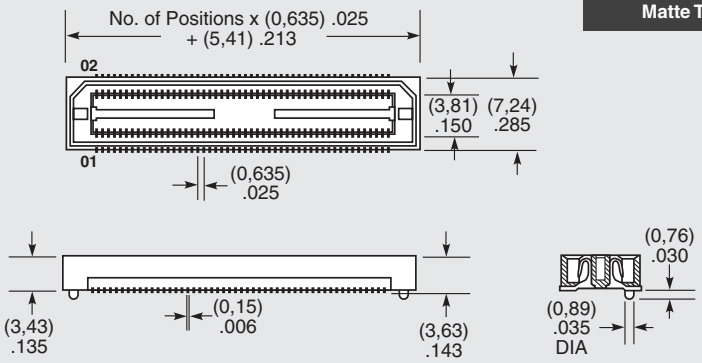
Mates with: BTS

–025, –050, –075, –100

–F = Gold Flash on contact, Matte Tin on tail

–L = 10µ" (0,25 µm) Gold on contact, Matte Tin on tail

–TR = Tape & Reel (–100 positions maximum)



Due to technical progress, all designs, specifications and components are subject to change without notice.